

SOT1707-1

LPGA740, plastic, low profile ball grid array; 740 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 1.05 mm body

28 August 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LPGA740
Package style descriptive code	LPGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-02-2016
Manufacturer package code	98ARE10587D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	37.5	-	mm
package width	-	37.5	-	mm
package height	-	1.05	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	740	-	



LPGA740, plastic, low profile ball grid array; 740 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 1.05 mm body

2 Package outline

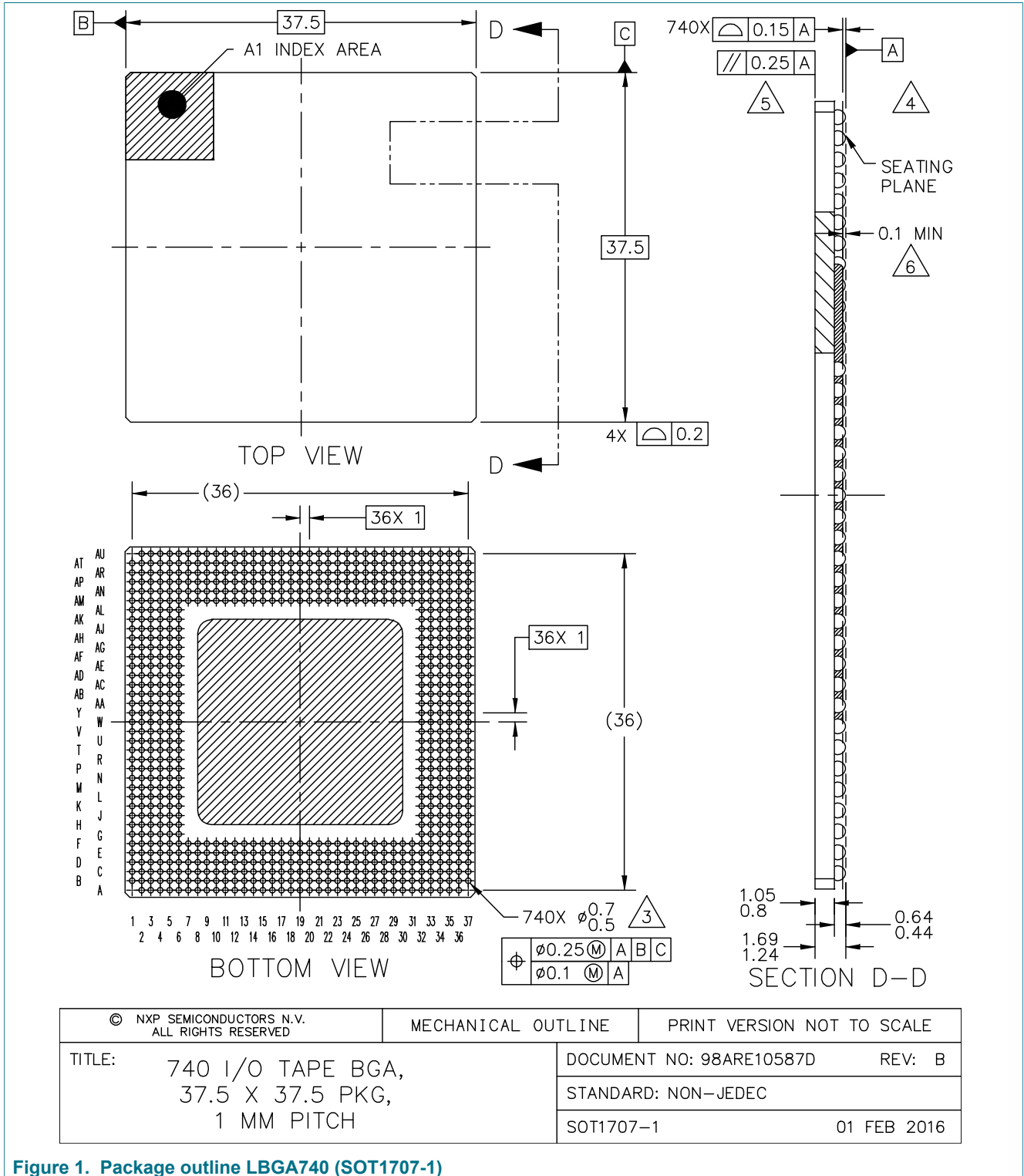


Figure 1. Package outline LPGA740 (SOT1707-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. DISTANCE FROM THE SEATING PLANE TO THE ENCAPSULANT MATERIAL.

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TITLE: 740 I/O TAPE BGA, 37.5 X 37.5 PKG, 1 MM PITCH	DOCUMENT NO: 98ARE10587D		REV: B
	STANDARD: NON-JEDEC		
	SOT1707-1		01 FEB 2016

Figure 2. Package outline note LPGA740 (SOT1707-1)

3 Legal information

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